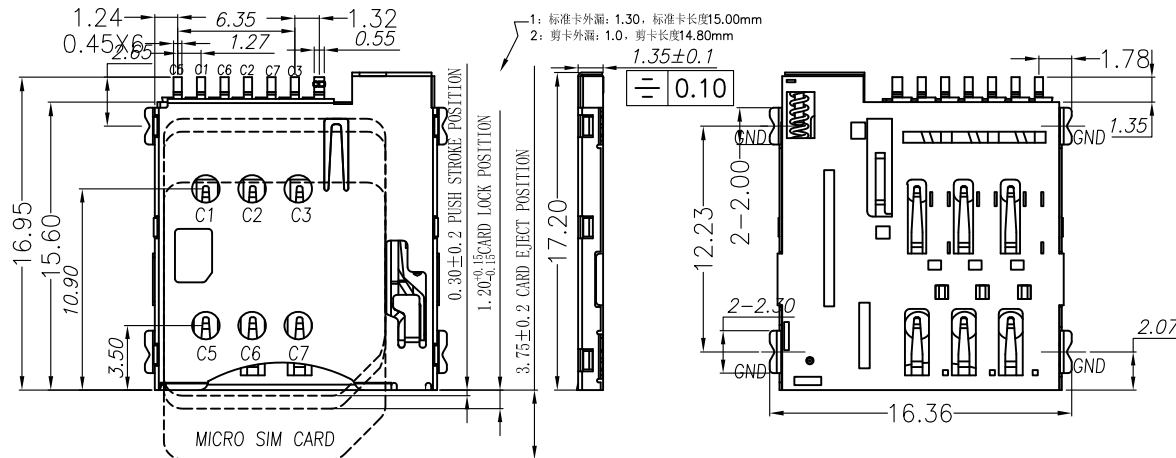
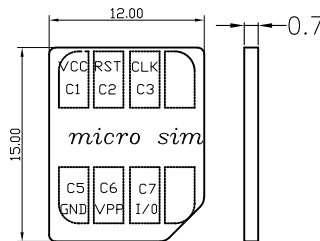
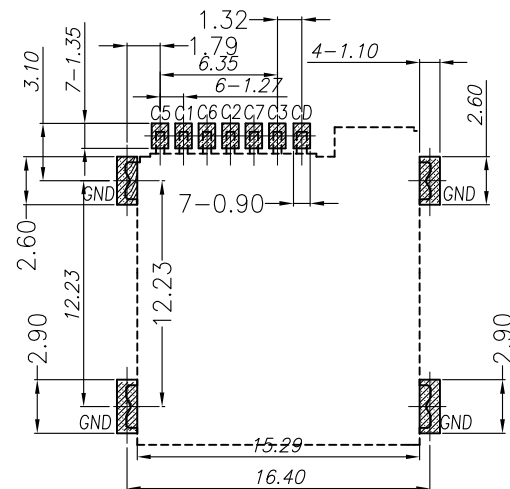
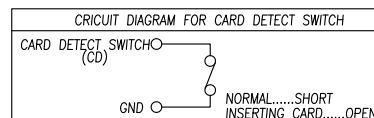


SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出



MICRO SIM CARD



PCB 焊盘区
下沉避位区

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
SHELL: SUS

PLATING:

Contact: Plated 50u'' Ni Overall Contact Au 1U
Shell: Plated 50u'' Ni Overall
Plated 1u''Au Selective Contact Area

Electrical:

Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100m Ω
Insulation Resistance:1000M min./500VΩ
产品耐温温度: 260
Mating Cycles:3000Min Insertions



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: MICRO SIM PUSH 6+1P	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HVC14-SIM07-135B	MOLD NO.
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HVC-SIM13112801	SHEET NO. 1 OF 1